

IN THE SPECIFICATION:

Page 6, please correct the paragraph beginning on line 5 to the following:

--First of all, for most processing plasmas, the electromagnetic propagation brings really a limitation in RF plasma processing for the substrate sizes of the order, or larger than 0.5 m^2 and especially larger than 1 m^2 , while the frequency of the RF source is higher than 10 MHz. More specifically, what is to be considered is the largest dimension of the substrate exposed to the plasma. If the substrate has a substantially square surface, said "largest dimension" is the diagonal of the square. So, any "largest dimension" higher than substantially 0.7 m is critical. Thus, the substrate for the present invention has a largest dimension of at least 0.7 m.--